Special Issue

Advanced Information Science and Distributed Systems

Message from the Guest Editor

We are thrilled to announce the launch of this Special Issue, which aims to deliver valuable insights into the ever-evolving fields of computer science and distributed systems. As these areas become increasingly crucial, we are dedicated to fostering exchange through this platform. Whether you are a researcher, academic, or industry professional, your participation is welcomed. This Special Issue explores cutting-edge technologies and applications spanning information security, artificial intelligence, quantum computing, digital life tech, machine learning, wireless communication, and more. We invite experts to join us in discussing and promoting the development of these fields. We expect to publish the latest research and future trends. Let us join forces to make everything around us better, one step at a time.

Guest Editor

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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multidimensional network.

Editor-in-Chief

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